

## SPECIFICATION FOR APPROVAL

### 3W, 2512, SL Type Low Resistance Chip Resistor (Lead / Halogen Free)

#### 1. Scope

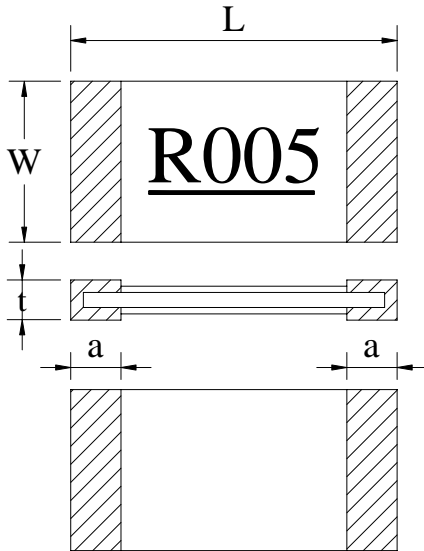
This specification applies to 3.2mm x 6.4mm size 3W, fixed metal foil current sensing resistors used in electronic equipment.

#### 2. Type Designation

RL32640W – □□□□ – □  
 (1) (2) (3)

Where (1) Series No.  
 (2) Resistance value :  
 For example :  
 Four digits of number  
 R005 = 5mΩ  
 (3) Tolerance :  
 Refer to paragraph 4

#### 3. Dimensions and schematic



Code Letter	Dimensions (mm)
	3264
L	6.35 ± 0.25
W	3.15 ± 0.25
a	0.95 ± 0.30
t	0.80 ± 0.20

Note: Marking (No Direction)

Figure 1. Construction and Dimensions



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4. Specification

Characteristics	Feature	
Power Rating*	3W	
Resistance Value	2~4 mΩ	5~50 mΩ
Temperature Coefficient of Resistance	± 200 ppm/°C	± 100 ppm/°C
Operation Temperature Range	-55°C ~ +170°C	
Resistance Tolerance	± 1%(F) , ± 2%(G) , ± 5%(J)	
Insulation Resistance	Over 100MΩ	
Maximum Working Voltage (V)	$(P \cdot R)^{1/2}$	

Note \* :

Power rating is based on continuous full load operation at rated ambient temperature of 70°C . For resistors operated at ambient temperature in excess of 70°C , the maximum load shall be derated in accordance with the following curve.

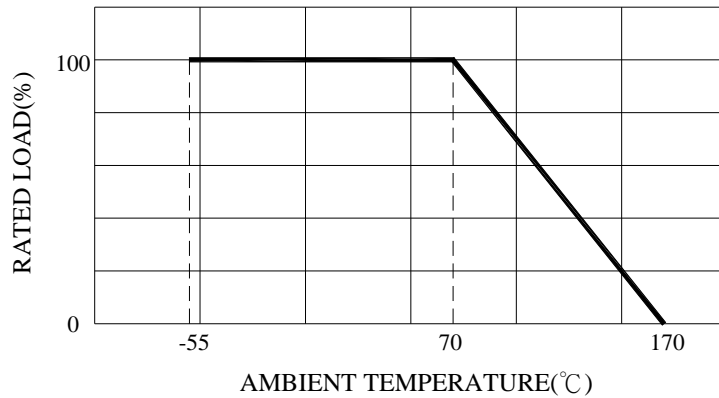


Figure 2. : Power Temperature Derating Curve



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**5. Reliability Performance**

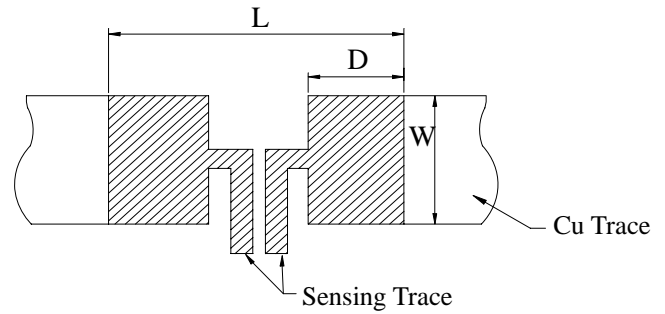
Test Item	Condition of Test	Requirements
Short Time Overload	5 x Rated power for 5 seconds Refer to JIS C 5201-1 4.13	$\Delta R : \pm 2.0\%$
Thermal Shock	-55 ~125°C 100 cycles, 15 min at each extreme condition Refer to JIS C 5201-1 4.19	$\Delta R : \pm 0.5\%$
Low Temperature Storage	Kept at -55°C, 1,000 hours Refer to JIS C 5201-1 4.23.4	$\Delta R : \pm 1.0\%$
Resistance to Soldering Heat	Dipped into solder at 270 ± 5°C for 20 ± 1 seconds Refer to JIS C 5201-1 4.18	$\Delta R : \pm 0.5\%$
Load Life	Rated voltage for 1.5hours followed by a pause 0.5hour at 70 ± 3°C Cycle repeated 1,000 hours Refer to JIS C 5201-1 4.25	$\Delta R : \pm 2.0\%$
Damp Heat with Load	40 ± 2°C with relative humidity 90% to 95%. D.C. rated voltage for 1.5 hours ON 30 minutes OFF. Cycle repeated 1,000 hours Refer to JIS C 5201-1 4.24	$\Delta R : \pm 1.0\%$
High Temperature Exposure	Kept at 170°C for 1,000 hours Refer to JIS C 5201-1 4.23.2	$\Delta R : \pm 1.0\%$
Solderability	Temperature of Solder : 245 ± 5°C Immersion Duration : 3 ± 0.5 second Refer to JIS C 5201-1 4.17	Uniform coating of solder cover minimum of 95% surface being immersed
Mechanical Shock	100 G's for 6milliseconds. 5 pulses Refer to JIS C 5201-1 4.21	$\Delta R : \pm 0.5\%$
Substrate Bending	Glass-Epoxy board thickness : 1.6mm Bending width : 2mm Between the fulcrums : 90mm Refer to JIS C 5201-1 4.33	$\Delta R : \pm 1.0\%$

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### 6. Recommended Solder Pad Dimensions

	W (mm)	L (mm)	D (mm)	t ( $\mu$ m)
3264	4.00	8.00	3.35	105

t: Copper foil minimum thickness of PCB



Note : We recommend there is no circuit design between pads to avoid circuit short

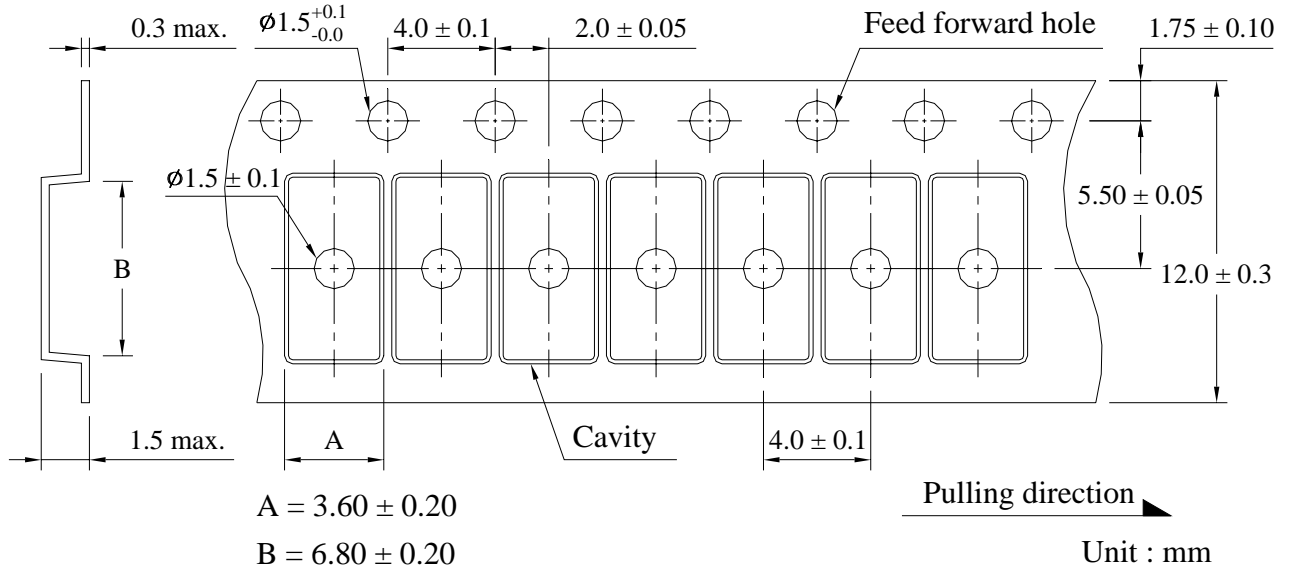


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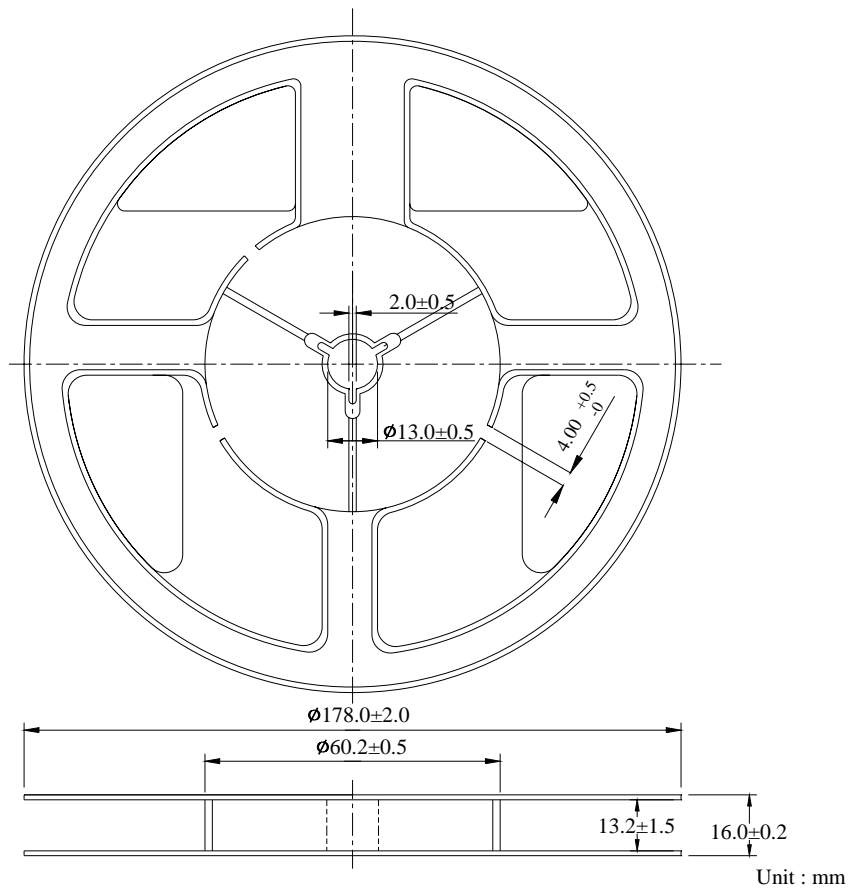
## 7. Packaging

### 7-1 Dimensions

#### 7-1-1 Tape packaging dimensions



#### 7-1-2 Reel dimensions

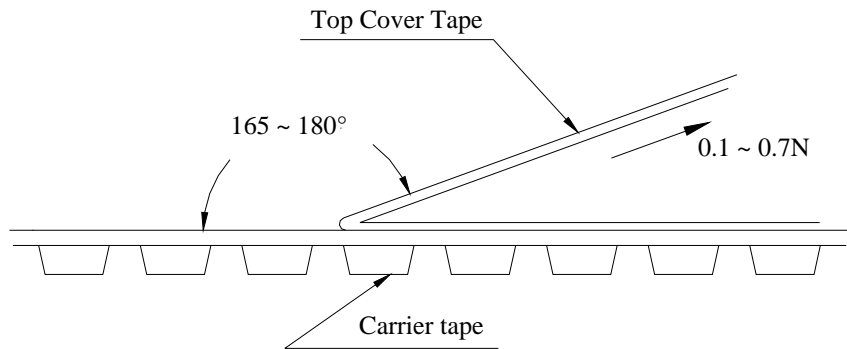


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### 7-2 Peel Strength of Top Cover Tape

The peel speed shall be about 300mm/min.

The peel force of top cover tape shall between 0.1 to 0.7N



### 7-3 Number of Taping

2,000 pieces / reel

### 7-4 Label marking

The following items shall be marked on the reel.

- (1) Type designation
- (2) Quantity
- (3) Manufacturing date code
- (4) Manufacturer's name
- (5) The country of origin